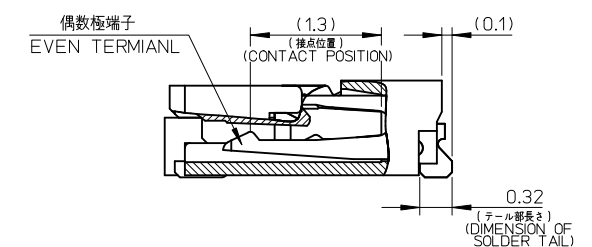
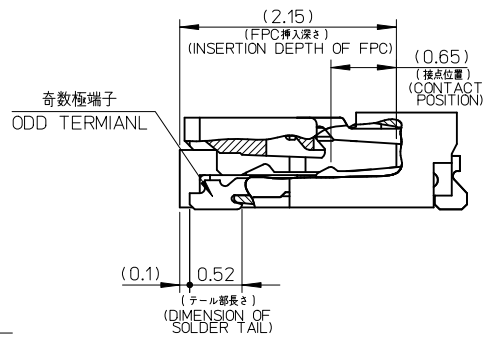
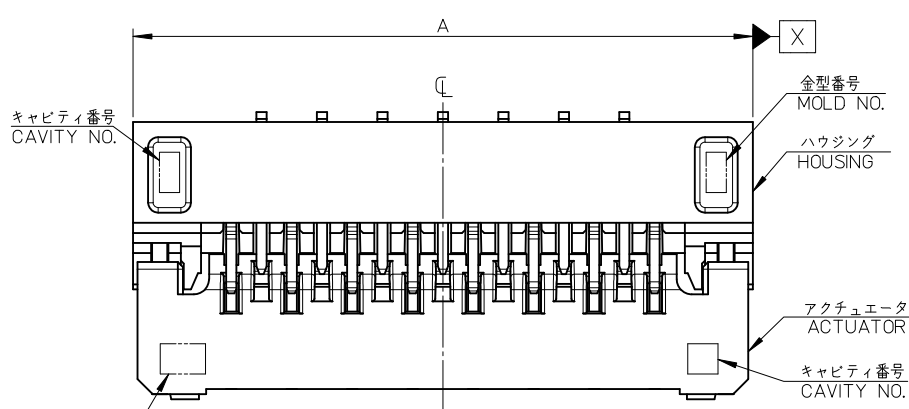
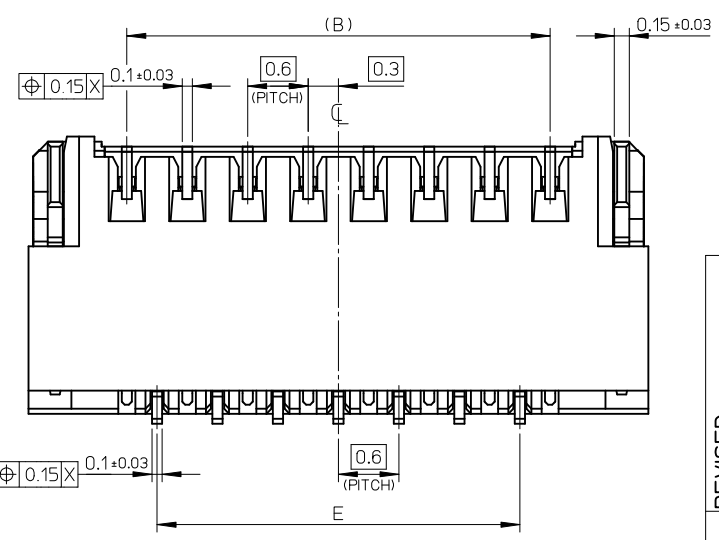
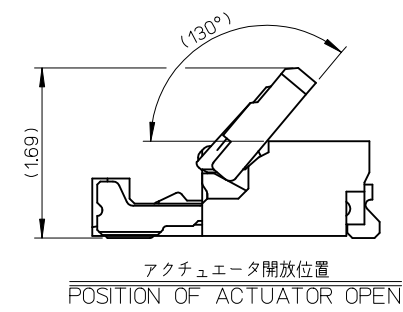
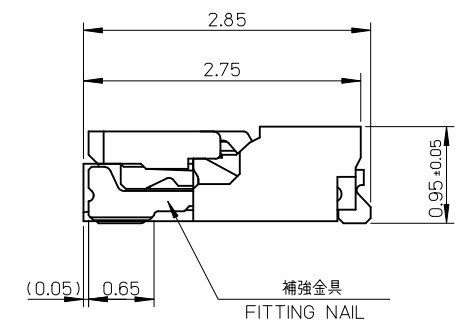
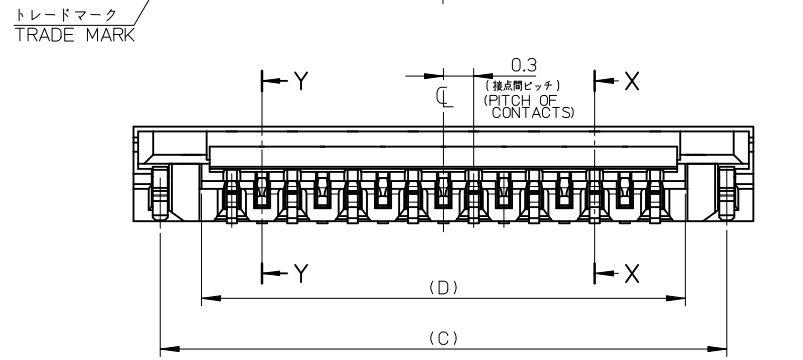


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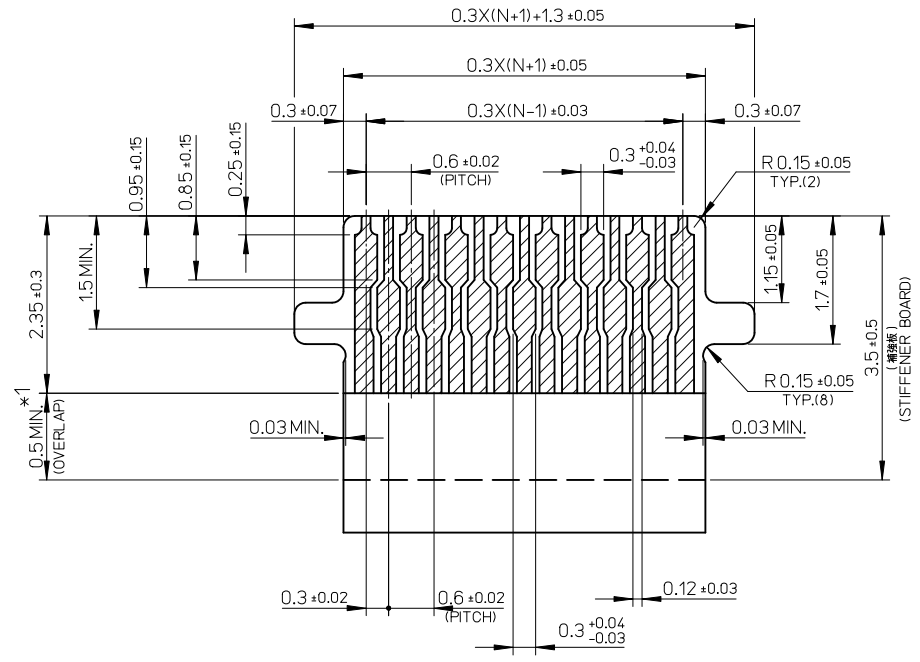
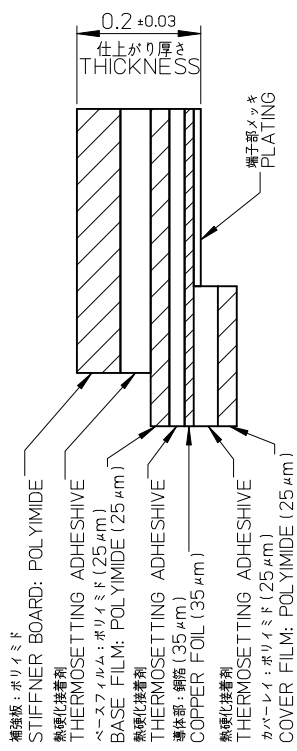
SECTION X-X

SECTION Y-Y

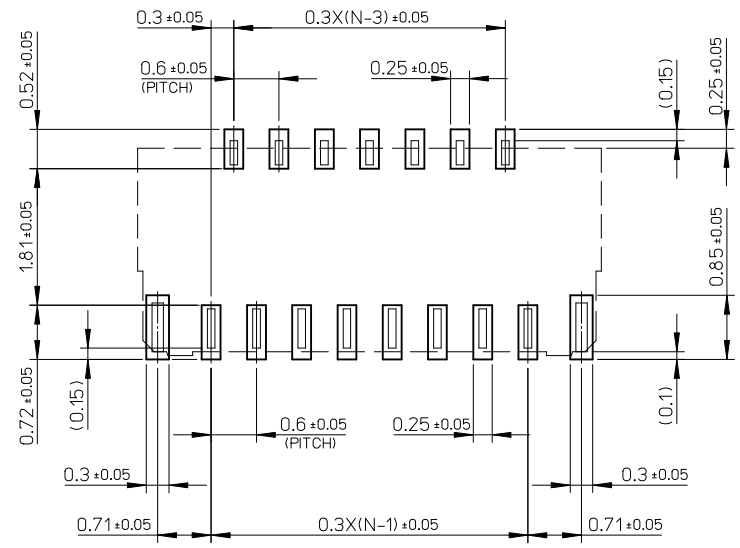


14.4	15.6	16.42	15.0	16.95	503566-5100	51
12.6	13.8	14.62	13.2	15.15	503566-4500	45
12.0	13.2	14.02	12.6	14.55	503566-4300	43
11.4	12.6	13.42	12.0	13.95	503566-4100	41
10.8	12.0	12.82	11.4	13.35	503566-3900	39
10.2	11.4	12.22	10.8	12.75	503566-3700	37
9.6	10.8	11.62	10.2	12.15	503566-3500	35
9.0	10.2	11.02	9.6	11.55	503566-3300	33
8.4	9.6	10.42	9.0	10.95	503566-3100	31
7.2	8.4	9.22	7.8	9.75	503566-2700	27
6.6	7.8	8.62	7.2	9.15	503566-2500	25
6.0	7.2	8.02	6.6	8.55	503566-2300	23
5.4	6.6	7.42	6.0	7.95	503566-2100	21
4.8	6.0	6.82	5.4	7.35	503566-1900	19
4.2	5.4	6.22	4.8	6.75	503566-1700	17
3.6	4.8	5.62	4.2	6.15	503566-1500	15
3.0	4.2	5.02	3.6	5.55	503566-1300	13
2.4	3.6	4.42	3.0	4.95	503566-1100	11
1.8	3.0	3.82	2.4	4.35	503566-0900	9
E	D	C	B	A	EMBOSSED PACKAGE	極数
					オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES NO. 503566-***8						

REVISED EC NO.: J2011-1637 DRWN: HMIYAMOTO 2011/05/31 CHKD: HIJIMA 2011/05/31 APPR: KMORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
	10 UNDER	± ---	DRAWN BY HIJIMA		DATE 2010/05/20		TITLE				
	10 OVER 30 UNDER	± ---	CHECKED BY NMATSUURA		DATE 2010/05/20		0.3 FPC CONN E/O BTM CONTACT TYPE HGT=0.95MM MOLEX INCORPORATED				
	30 OVER	± ---	APPROVED BY KMORIKAWA		DATE 2010/06/11						
	ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. 503566-***8		DOCUMENT NO. SD-503566-001		SHEET NO. 1 OF 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											



適合するFPC推奨寸法 (参考)
APPLICABLE FPC
PATTERN DIMENSIONS(REF.)
(端子部仕上がり厚さ: 0.2±0.03)
(THICKNESS: 0.2±0.03)



参考基板レイアウト
RECOMMENDED PCB
PATTERN DIMENSIONS(REF.)

推奨ペースト厚 : 100µm
推奨マスク開口率 : 80%
RECOMMEND SCREEN THICKNESS : 100µm
RECOMMEND SCREEN OPEN RATIO : 80%

注記 NOTES

- 使用材料 MATERIALS
ハウジング : 液晶ポリマー (LCP)、ガラス充填、UL94V-0、ナチュラル (白色系)
アクチュエータ: ポリアミド (PA)、ガラス充填、UL94V-HB、黒色
奇数端子 : 燐青銅、ニッケル下地、金メッキ
偶数端子 : 燐青銅、ニッケル下地、金メッキ
補強金具 : 燐青銅、ニッケル下地、金メッキ
HOUSING : LIQUID CRYSTAL POLYMER(LCP), GLASS FILLED
UL94V-0, NATURAL(WHITE)
ACTUATOR : POLYAMIDE (PA), GLASS FILLED
UL94V-HB, BLACK
ODD TERMINAL : PHOSPHOR BRONZE, Gold OVER Nickel PLATING
EVEN TERMINAL : PHOSPHOR BRONZE, Gold OVER Nickel PLATING
FITTING NAIL : PHOSPHOR BRONZE, Gold OVER Nickel PLATING
- 端子、補強金具のコプラナリティは 0.1以下とする
COPLANALITY OF SOLDER TAILS AND FITTING NAILS: 0.1MAX.
- 一般公差: ± 0.3
GENERAL TOLERANCES: ±0.3
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

FPC構成推奨仕様
STRUCTURE OF FPC

・FPCについて (ABOUT FPC)

抜き方向は、導体側から補強板側を推奨します
補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します
なお、接着剤の接点部への付着は導通不良の原因となりますので
染み出しがないよう、お願いします

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE
RECOMMENDED MATERIAL:
STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING ADHESIVE
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON
ADHEREND BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY

・FPCパターンメッキ仕様

金メッキ: 0.1µm 以上
下地ニッケルメッキ: 2~6µm
FPC PATTERN PLATING
GOLD PLATING : 0.1µm MINIMUM
NICKEL UNDER PLATING : 2~6µm

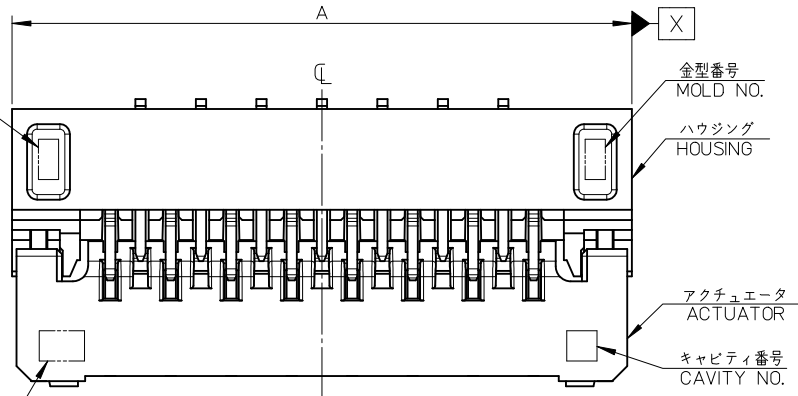
*1 補強板長さが図面通り確保できない場合は、カバーレイと
補強板のオーバーラップ寸法を0.5mm以上としてください
WHEN STIFFENER BOARD DIMENSION CAN NOT
SECURE AS DRAWING, PLEASE GIVE THE OVERLAP
SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM

SEE SHEET 1 OF 2 EC NO: J2011-1637 DRAWN: YAMOTO CHKD: IJIMA APPR: KMORIKAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY HIJIMA	DATE 2010/05/20	TITLE 0.3 FPC CONN E/O BTM CONTACT TYPE HGT=0.95MM		
	10 OVER 30 UNDER	± ---	CHECKED BY NMATSUURA	DATE 2010/05/20	MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2010/06/11	MATERIAL NO. 503566-***8		
ANGULAR	±1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DOCUMENT NO. SD-503566-001		SHEET NO. 2 OF 2	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

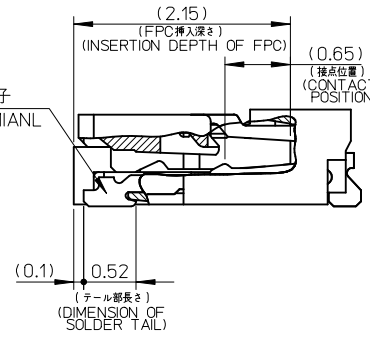
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キャビティ番号
CAVITY NO.

トレードマーク
TRADE MARK

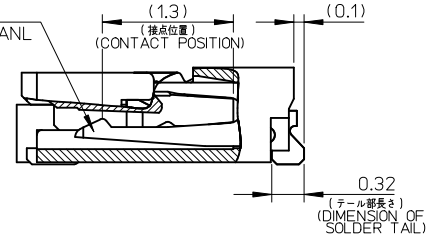


奇数極端子
ODD TERMINAL

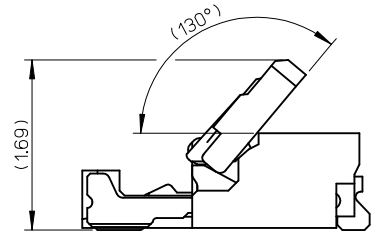
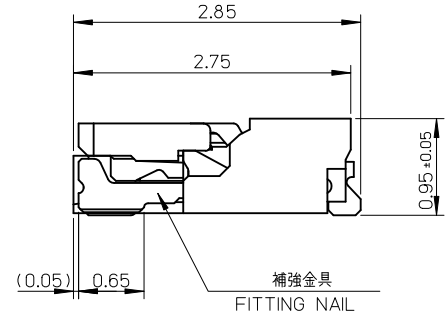
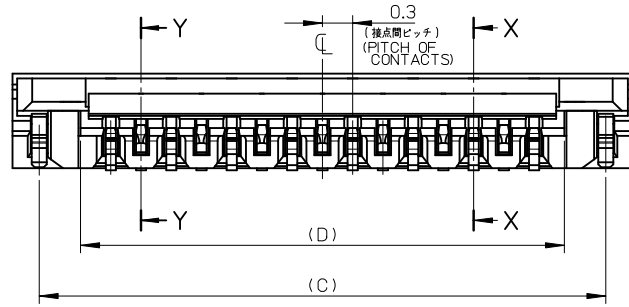


SECTION X-X

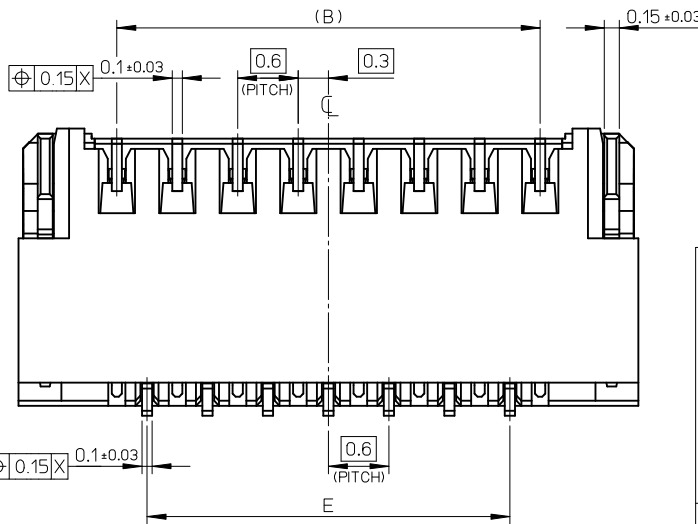
偶数極端子
EVEN TERMINAL



SECTION Y-Y

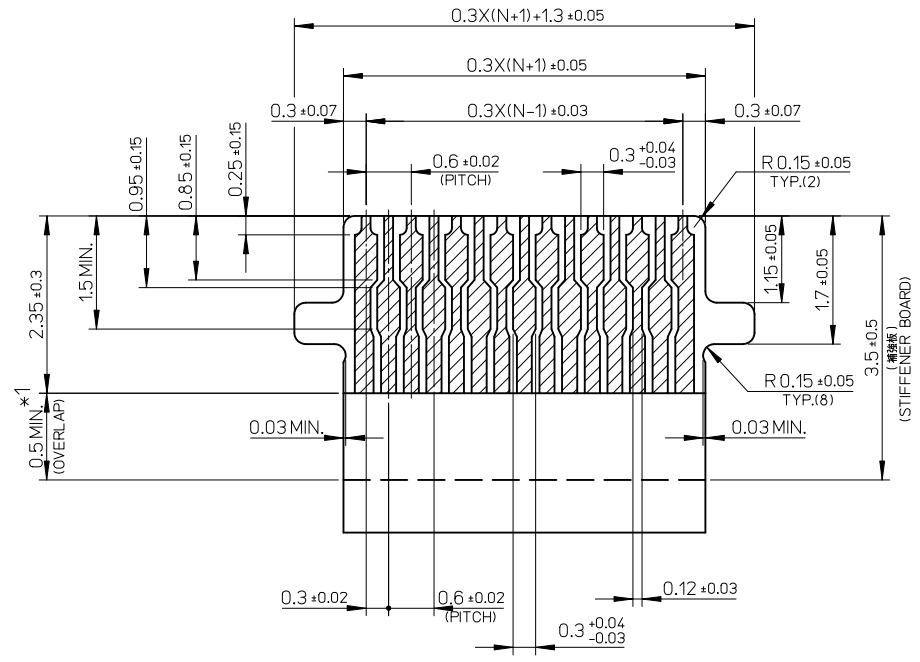
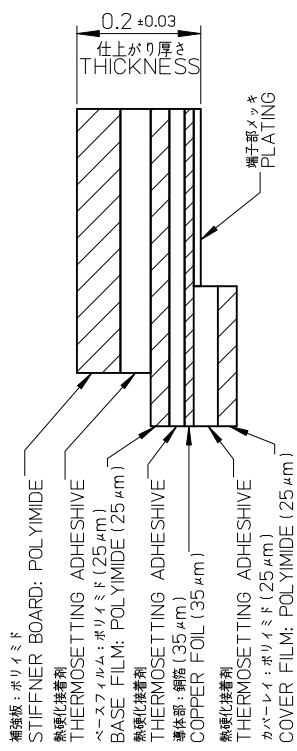


アクチュエータ開放位置
POSITION OF ACTUATOR OPEN

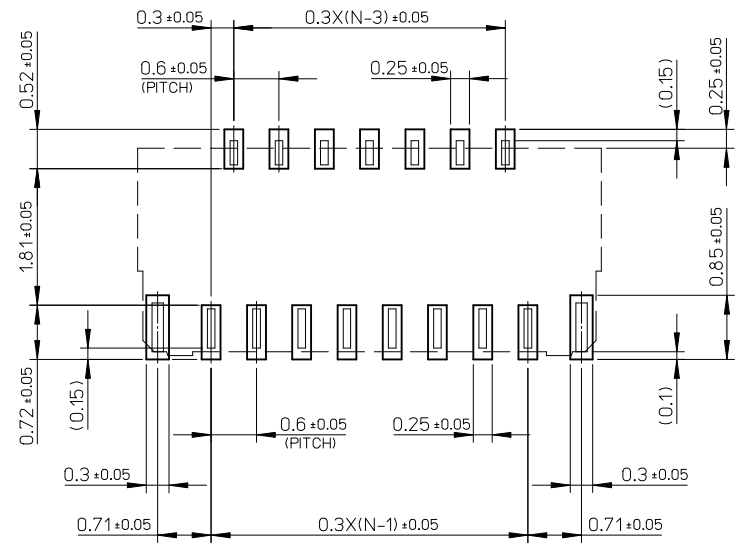


14.4	15.6	16.42	15.0	16.95	503566-5100	51
12.6	13.8	14.62	13.2	15.15	503566-4500	45
12.0	13.2	14.02	12.6	14.55	503566-4300	43
11.4	12.6	13.42	12.0	13.95	503566-4100	41
10.8	12.0	12.82	11.4	13.35	503566-3900	39
10.2	11.4	12.22	10.8	12.75	503566-3700	37
9.6	10.8	11.62	10.2	12.15	503566-3500	35
9.0	10.2	11.02	9.6	11.55	503566-3300	33
8.4	9.6	10.42	9.0	10.95	503566-3100	31
7.2	8.4	9.22	7.8	9.75	503566-2700	27
6.6	7.8	8.62	7.2	9.15	503566-2500	25
6.0	7.2	8.02	6.6	8.55	503566-2300	23
5.4	6.6	7.42	6.0	7.95	503566-2100	21
4.8	6.0	6.82	5.4	7.35	503566-1900	19
4.2	5.4	6.22	4.8	6.75	503566-1700	17
3.6	4.8	5.62	4.2	6.15	503566-1500	15
3.0	4.2	5.02	3.6	5.55	503566-1300	13
2.4	3.6	4.42	3.0	4.95	503566-1100	11
1.8	3.0	3.82	2.4	4.35	503566-0900	9
E	D	C	B	A	EMBOSSED PACKAGE	極数
					オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES NO. 503566-***8						

REVISED EC NO.: J2011-1637 DRWN: HMIYAMOTO 2011/05/31 CHKD: H IJIMA 2011/05/31 APPR: KMORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
	10 UNDER	± ---	DRAWN BY HIJIMA		DATE 2010/05/20		TITLE 0.3 FPC CONN E/O BTM CONTACT TYPE HGT=0.95MM				
	10 OVER 30 UNDER	± ---	CHECKED BY NMATSUURA		DATE 2010/05/20		MOLEX INCORPORATED DOCUMENT NO. SD-503566-001 SHEET NO. 1 OF 2				
	30 OVER	± ---	APPROVED BY KMORIKAWA		DATE 2010/06/11						
	ANGULAR ±1 °		MATERIAL NO. 503566-***8		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS											



適合するFPC推奨寸法 (参考)
APPLICABLE FPC
PATTERN DIMENSIONS(REF.)
(端子部仕上がり厚さ: 0.2±0.03)
(THICKNESS: 0.2±0.03)



参考基板レイアウト
RECOMMENDED PCB
PATTERN DIMENSIONS(REF.)

推奨ペースト厚 : 100µm
推奨マスク開口率 : 80%
RECOMMEND SCREEN THICKNESS : 100µm
RECOMMEND SCREEN OPEN RATIO : 80%

注記 NOTES

- 使用材料 MATERIALS
ハウジング : 液晶ポリマー (LCP)、ガラス充填、UL94V-0、ナチュラル (白色系)
アクチュエータ: ポリアミド (PA)、ガラス充填、UL94V-HB、黒色
奇数端子 : 燐青銅、ニッケル下地、金メッキ
偶数端子 : 燐青銅、ニッケル下地、金メッキ
補強金具 : 燐青銅、ニッケル下地、金メッキ
HOUSING : LIQUID CRYSTAL POLYMER(LCP), GLASS FILLED
UL94V-0, NATURAL(WHITE)
ACTUATOR : POLYAMIDE (PA), GLASS FILLED
UL94V-HB, BLACK
ODD TERMINAL : PHOSPHOR BRONZE, Gold OVER Nickel PLATING
EVEN TERMINAL : PHOSPHOR BRONZE, Gold OVER Nickel PLATING
FITTING NAIL : PHOSPHOR BRONZE, Gold OVER Nickel PLATING
- 端子、補強金具のコプラナリティは 0.1以下とする
COPLANALITY OF SOLDER TAILS AND FITTING NAILS: 0.1MAX.
- 一般公差: ± 0.3
GENERAL TOLERANCES: ±0.3
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

FPC構成推奨仕様
STRUCTURE OF FPC

FPCについて (ABOUT FPC)

抜き方向は、導体側から補強板側を推奨します
補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します
なお、接着剤の接点部への付着は導通不良の原因となりますので
染み出しがないよう、お願いします

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE
RECOMMENDED MATERIAL:
STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING ADHESIVE
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON
ADHEREND BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY

FPCパターンメッキ仕様

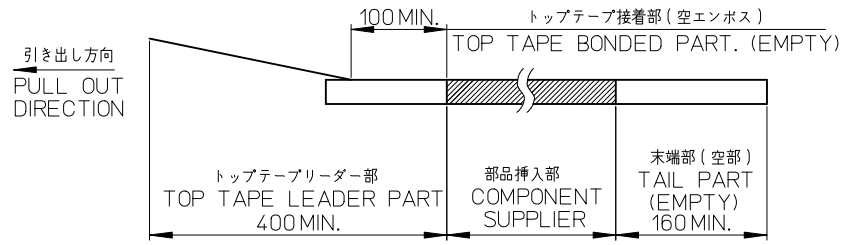
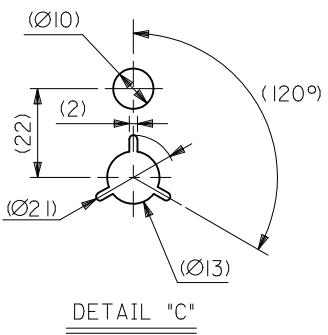
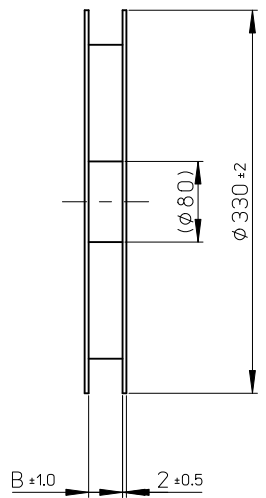
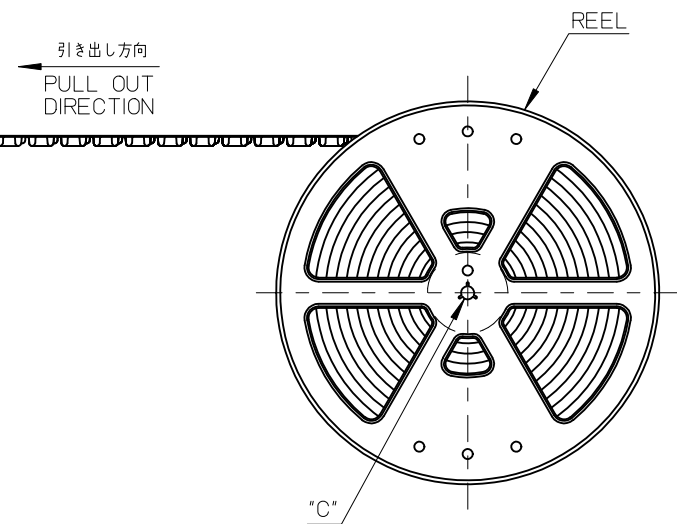
金メッキ: 0.1µm 以上
下地ニッケルメッキ: 2~6µm
FPC PATTERN PLATING
GOLD PLATING : 0.1µm MINIMUM
NICKEL UNDER PLATING : 2~6µm

*1 補強板長さが図面通り確保できない場合は、カバーレイと
補強板のオーバーラップ寸法を0.5mm以上としてください
WHEN STIFFENER BOARD DIMENSION CAN NOT
SECURE AS DRAWING, PLEASE GIVE THE OVERLAP
SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM

SEE SHEET 1 OF 2 EC NO: J2011-1637 DRAWN: YAMOTO CHKD: IJIMA APPR: KMORIKAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY		METRIC	
	10 UNDER	± ---	DRAWN BY	DATE	TITLE	
	10 OVER 30 UNDER	± ---	HIIJIMA	2010/05/20	0.3 FPC CONN E/O BTM CONTACT TYPE HGT=0.95MM	
30 OVER	± ---	CHECKED BY	DATE	MOLEX INCORPORATED		
ANGULAR	±1 °	APPROVED BY	DATE		MATERIAL NO.	DOCUMENT NO.
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		503566-***8		SD-503566-001		2 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

注記 NOTES

1. 製品詳細寸法については図面 SD-503566-001 を参照下さい。
RE DETAILED DIMENSION, SEE SD-503566-001
2. 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
3. リードテープ長さ LEAD TAPE LENGTH



4. 材料 MATERIAL
 キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)
 トップテープ (TOP TAPE) : PET , PE , PEF
 リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
 POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
5. トップテープの剝離強度については、IEC60286-3に準拠
 TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.

REVISED EC NO: J2011-1637 DRWN: HIYAMOTO 2011/05/31 CHKD: HIJIMA 2011/05/31 APPR: KMORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 503566-**00
	10 UNDER	±0.2	DRAWN BY HIJIMA	DATE 2010/05/20	TITLE 0.3 FPC CONN. E/O TAPING PACKAGE (503566-**08 SERIES)		
	10 OVER 30 UNDER	±0.25	CHECKED BY NMATSUURA	DATE 2010/05/20	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2010/06/11	DOCUMENT NO. SD-503566-002	SHEET NO. 1 OF 2	
	ANGULAR ±3 °		MATERIAL NO. SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

F

E

D

C

B

A

F

E

D

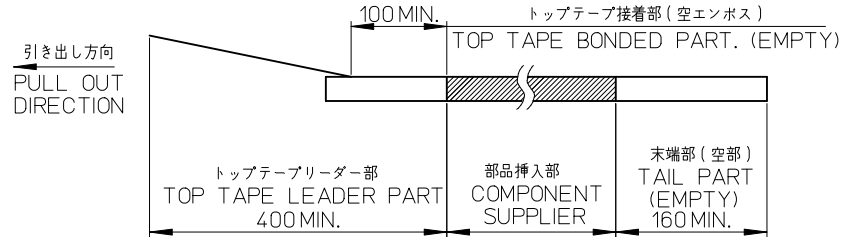
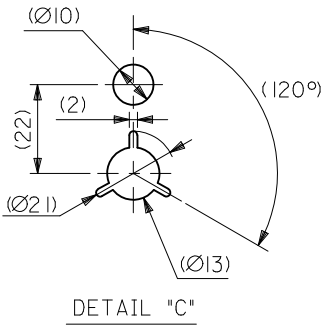
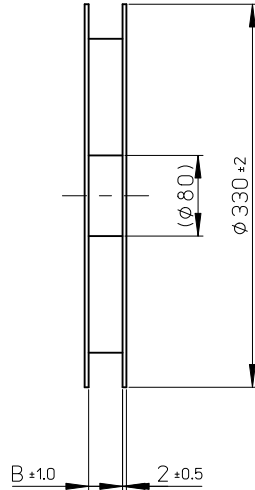
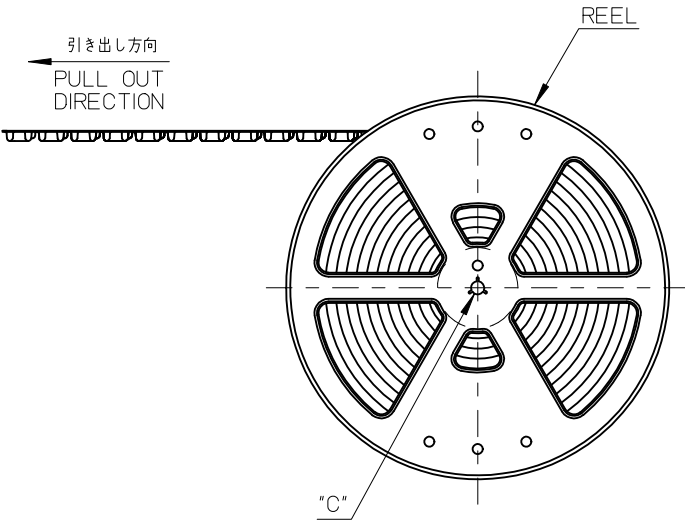
C

B

A

注記 NOTES

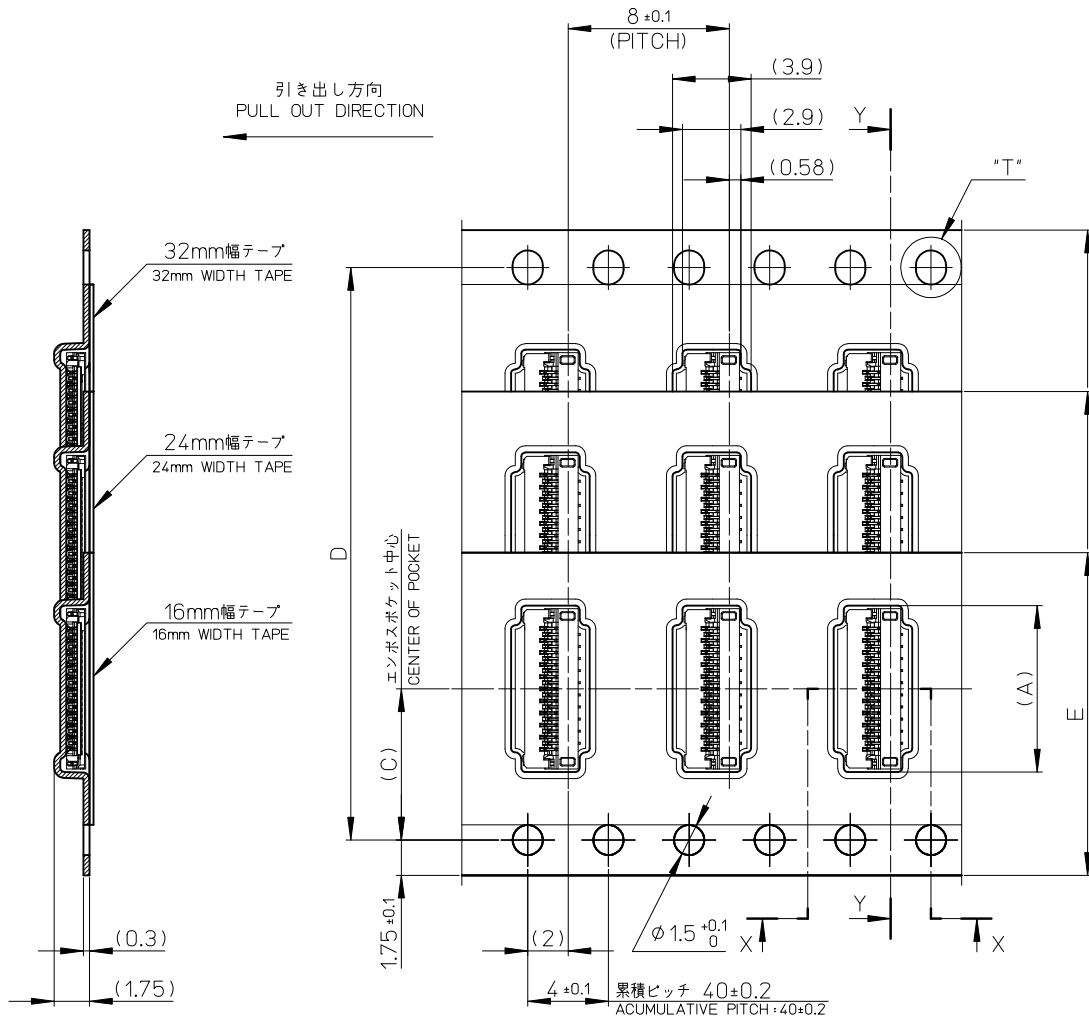
- 製品詳細寸法については図面 SD-503566-001 を参照下さい。
RE DETAILED DIMENSION, SEE SD-503566-001
- 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



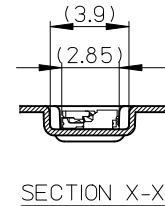
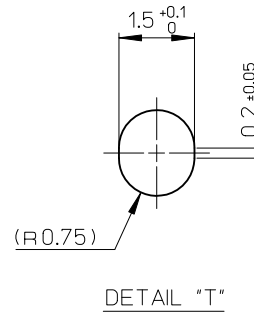
- 材料 MATERIAL
 キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)
 トップテープ (TOP TAPE) : PET , PE , PEF
 リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
 POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- トップテープの剝離強度については、IEC60286-3に準拠
 TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.

MODEL NO. 503566-**00

REVISED EC NO: J2011-1637 DRWN: HIYAMOTO 2011/05/31 CHKD: HIJIMA 2011/05/31 APPR: KMORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY HIJIMA	DATE 2010/05/20	TITLE 0.3 FPC CONN. E/O TAPING PACKAGE (503566-**08 SERIES)			
	10 OVER 30 UNDER	±0.25	CHECKED BY NMATSUURA	DATE 2010/05/20	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2010/06/11	DOCUMENT NO. SD-503566-002			
	ANGULAR ±3 °		MATERIAL NO. SEE CHART		SHEET NO. 1 OF 2			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

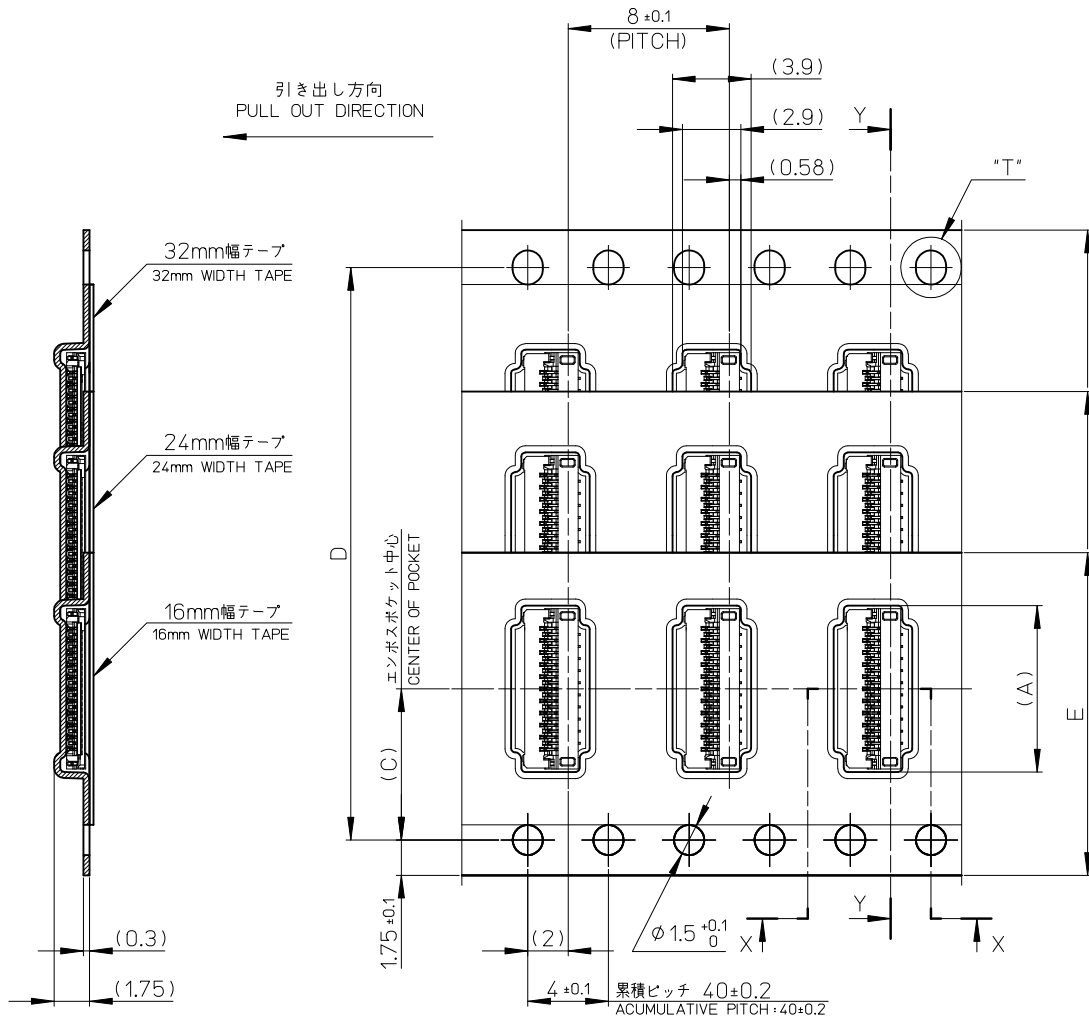


SECTION Y-Y

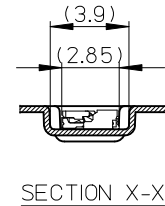
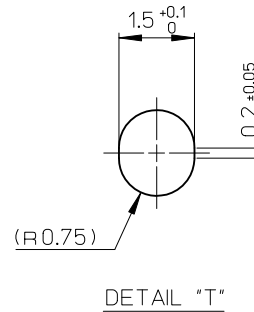


32±0.3	28.4	14.2	33.4	17.25	503566-5100	51
24±0.3	—	11.5	25.4	15.45	503566-4500	45
				14.85	503566-4300	43
				14.25	503566-4100	41
				13.65	503566-3900	39
				13.05	503566-3700	37
				12.45	503566-3500	35
				11.85	503566-3300	33
				11.25	503566-3100	31
				10.65	503566-2900	29
				10.05	503566-2700	27
16±0.3	—	7.5	17.4	9.45	503566-2500	25
				8.85	503566-2300	23
				8.25	503566-2100	21
				7.65	503566-1900	19
				7.05	503566-1700	17
				6.45	503566-1500	15
				5.85	503566-1300	13
				5.25	503566-1100	11
4.65	503566-0900	9				
E キャリアテープ幅 EMBOSSED TAPE WIDTH	D	C	B	A	EMBOSSED TAPE PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

SEE SHEET 1 OF 2 EC NO: J2011-1637 DRWN: HMIYAMOTO 2011/05/31 CHKD: HIJIMA 2011/05/31 APPR: KMORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HIJIMA	DATE 2010/05/20	TITLE 0.3 FPC CONN. E/O TAPING PACKAGE (503566-**08 SERIES)		
	10 OVER 30 UNDER	±0.25	CHECKED BY NMATSUURA	DATE 2010/05/20	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2010/06/11	DOCUMENT NO. SD-503566-002	SHEET NO. 2 OF 2	
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



SECTION Y-Y



32±0.3	28.4	14.2	33.4	17.25	503566-5100	51
24±0.3	—	11.5	25.4	15.45	503566-4500	45
				14.85	503566-4300	43
				14.25	503566-4100	41
				13.65	503566-3900	39
				13.05	503566-3700	37
				12.45	503566-3500	35
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				11.25	503566-3100	31
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				7.65	503566-1900	19
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E キャリアテープ幅 EMBOSSED TAPE WIDTH	D	C	B	A	EMBOSSED TAPE PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

SEE SHEET 1 OF 2 EC NO: J2011-1637 DRWN: HMIYAMOTO 2011/05/31 CHKD: HIJIMA 2011/05/31 APPR: KMORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
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ANGULAR	±3 °	MATERIAL NO.		SEE CHART			
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